**Plastic Packages for Integrated Circuits**

**Package Outline Drawing**

**W11x11.121A**

121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm pitch) (BSC)

Rev 1, 2/14

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**NOTES:**

1. All dimensions are in millimeters.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.